

# MUTE 2010

21<sup>st</sup> Micromechanics and  
Micro systems Europe Workshop

## Programme



## Programme

### Sunday September 26 2010

18:00 – 20:00 : Registration, buffet  
20:00 – 00:00 : Concert in Atak

### Monday September 27 2010

8:30 – 9:00 : Registration  
9:00 – 9:15 : Welcome  
9:15 – 10:00 : Invited Speaker 1

#### **Understanding and eliminating nanoscale wear**

M.A. Lanz

IBM Research Division, Zurich Research Laboratory, Switzerland

10:00 – 11:00 : Flash presentation [Session A](#) (25 x 2 min)  
11:00 – 12:30 : Poster [Session A](#)  
12:30 – 14:15 : Lunch  
14:15 – 15:00 : Invited Speaker 2

#### **Optical sensors and actuators enabled by photonic crystals**

O. Solgaard

Stanford University, E.L. Ginzton Laboratory, CA, USA

15:00 – 16:00 : Flash presentation [Session B](#) (25 x 2 min)  
16:00 – 18:00 : Poster [Session B](#)

19:00 – 20:00 : Reception and Grolsch Veste tour  
20:00 – 23:00 : Conference Dinner

### Tuesday September 28 2010

8:30 – 9:00 : Registration  
9:00 – 9:45 : Invited Speaker 3

#### **Programmed self-assembly and dynamics of DNA nanostructures**

K.V. Gothelf

Aarhus University, Denmark

9:45 – 10:45 : Flash presentation [Session C](#) (25 x 2 min)  
10:45 – 12:15 : Poster [Session C](#)  
12:15 – 14:00 : Lunch  
14:00 – 14:45 : Invited Speaker 4

#### **Glass-based lab-on-a-chip products**

R. van 't Oever

Micronit, Enschede, The Netherlands

14:45 – 15:45 : Flash presentation [Session D](#) (25 x 2 min)  
15:45 – 17:15 : Poster [Session D](#)  
17:15 – 17:45 : MME2011, poster award and closing remarks

20:00 – ? : Science Cafe and excursion in Enschede

### Wednesday September 29 2010

9:00 – 12:30 : MESA+ NanoLab tours

Session A  
(Monday 10:00 – 12:30)

A01

**Silicon carbide thin-film encapsulation of planar thermo- electric infrared (IR) detectors - for an IR microspectrometer**

V. Rajaraman, G. de Graaf, P.J. French and K.A.A. Makinwa

Delft University of Technology (TU Delft), Dept. of Microelectronics, EI Lab - DIMES, The Netherlands

A02

**Design, fabrication and characterization of an in-plane AFM probe with ultra-sharp silicon nitride tip**

E. Sarajlic<sup>1</sup>, J. Geerlings<sup>2</sup>, J.W. Berenschot<sup>2</sup>, M.H. Siekman<sup>1,2</sup>, N.R. Tas<sup>2</sup> and L. Abelmann<sup>2</sup>

<sup>1</sup>SmartTip, Enschede, The Netherlands <sup>2</sup>MESA+ Research Institute, University of Twente, The Netherlands

A03

**A silicon micromachined triaxial accelerometer using the MultiMEMS MPW process with additional deep reactive ion etching as post-processing**

P. Ohlckers, L. Petricca and C. Grinde

Vestfold University College, Institute for Micro- and nano System Technologies, Norway

A04

**Integrated Lab-On-A-Chip silicon nanowire biosensing platform**

A. De, S. Chen, J. van Nieuwkasteele, W. Sparreboom, E.T. Carlen and A. van den Berg

BIOS Lab on a Chip Group, MESA+ Institute for Nanotechnology, University of Twente, The Netherlands

A05

**Surface modification of silicon by 3D etching processes and subsequent layer deposition**

Z. Fekete, D. Gubán, É. Vázsonyi, A. Pongrácz, G. Battistig and P. Fürjes

Research Institute of Technical Physics & Materials Science, Hungarian Academy of Science, Hungary

A06

**Material selection for impedance spectroscopy on an eletrowetting based Lab-On-A-Chip**

T. Lederer, S. Clara, B. Jakoby and W. Hilber

Institute for Microelectronics and Microsensors, Johannes Kepler University, Austria

A07

**Stiction reduction in electrostatic poly-SiGe micromirrors by applying a self-assembled monolayer film**

L. Fangzhou<sup>1,2</sup>, J. De Coster<sup>1</sup>, R. Beernaert<sup>3</sup>, W.-Y. Lin<sup>1,2</sup>, J.-P. Celis and J.-P. Celis

<sup>1</sup>IMEC, Belgium <sup>2</sup>Dept MTM, KU Leuven, Belgium <sup>3</sup>CMST, Ghent University, Belgium

A08

**A bridge-connected isolated silicon islands post-processing method for fine-grain-integrated 10V-operating CMOS-MEMS by standard 5V CMOS process technology**

S. Morishita<sup>1</sup>, M. Kubota<sup>1</sup>, K. Asada<sup>1</sup>, I. Mori<sup>1</sup>, F. Marty<sup>2</sup> and Y. Mita<sup>1</sup>

<sup>1</sup>The University of Tokyo, Japan <sup>2</sup>ESIEE, Universit Paris Est, France

A09

**Single-mask thermal displacement sensor in MEMS**

B. Krijnen<sup>1,2</sup>, R.P. Hogervorst<sup>1</sup>, J.B.C. Engelen<sup>3</sup>, J.W. van Dijk<sup>1,2</sup>, D.M. Brouwer<sup>1,2</sup> and L. Abelmann<sup>3</sup>

<sup>1</sup>DEMCON Advanced Mechatronics, The Netherlands <sup>2</sup>Mechanical Automation, IMPACT, University of Twente, The Netherlands <sup>3</sup>Transducer Science and Technology, MESA+, University of Twente, The Netherlands

A10

**AlGaIn/GaN C-HEMT for piezoelectric MEMS stress sensor applications**

M. Vallo<sup>1</sup>, T. Lalinský<sup>1</sup>, G. Vanko<sup>1</sup>, M. Držík<sup>2</sup>, S. Hascik<sup>1</sup>, I. Rýger<sup>1</sup> and I. Kostic<sup>3</sup>

<sup>1</sup>Institute of Electrical Engineering of the Slovak Academy of Sciences, Slovakia <sup>2</sup>International Laser Center, Slovakia <sup>3</sup>Institute of Informatics, Slovak Academy of Sciences, Slovakia

A11

**A capacitive humidity sensor using a positive photosensitive polymer**

N. P. Pham, V. Cherman, F.F.C. Duval, D.S. Tezcan, R. Jansen and H.A.C. Tilmans  
IMEC, Belgium

A12

**Silicon/glass microchip with a monolithically integrated electrospray ionization tip for mass spectrometry**

L. Sainiemi<sup>1</sup>, T. Nissilä<sup>2,3</sup>, V. Saarela<sup>4</sup>, R.A. Ketola<sup>3</sup> and S. Franssila<sup>1</sup>

<sup>1</sup>Aalto University, Department of Materials Science and Engineering, Finland <sup>2</sup>University of Helsinki, Division of Pharmaceutical Chemistry, Finland <sup>3</sup>University of Helsinki, Centre for Drug Research (CDR), Finland <sup>4</sup>Aalto University, Department of Micro and Nanosciences, Finland

A13

**Improving the efficiency of thermoelectric generators by using solar heat concentrators**

M.T. de Leon, P. Taatizadeh and M. Kraft

University of Southampton, School of Electronics and Computer Science, United Kingdom

A14

**Gas sensing micromachined structure based on gallium arsenide**

I. Hotovy<sup>1</sup>, D. Tengeri<sup>1</sup>, V. Rehacek<sup>1</sup>, S. Hascik<sup>2</sup> and T. Lalinský<sup>1</sup>

<sup>1</sup>Microelectronics Department, Slovak University of Technology, Slovakia <sup>2</sup>Institute of Electrical Engineering, Slovak Academy of Sciences, Slovakia

A15

**Structuring techniques of aluminum nitride masks for deep reactive ion etching (DRIE) of silicon**

S. Leopold<sup>1</sup>, T. Polster<sup>1</sup>, T. Geiling<sup>1</sup>, D. Pätz<sup>2</sup>, F. Knöbber<sup>4</sup>, A. Albrecht<sup>3</sup>, O. Ambacher<sup>4</sup>, S. Sinzinger<sup>2</sup> and M. Hoffmann<sup>1</sup>

<sup>1</sup>Ilmenau University of Technology, IMN MacroNano, Germany, Department for Micromechanical Systems <sup>2</sup>Department for Optical Engineering <sup>3</sup>Centre for Micro- and Nanotechnology <sup>4</sup>Fraunhofer Institute for Applied Solid State Physics, Germany

A16

**Design and evaluation of an active cooling concept for functional ceramic circuits**

T. Haas<sup>1</sup>, C. Zeilmann<sup>1</sup>, A. Backes<sup>2</sup>, A. Bittner<sup>3</sup> and U. Schmid<sup>3</sup>

<sup>1</sup>Engineering Substrate, Micro Systems Engineering GmbH, Germany <sup>2</sup>Chair of Micromechanics, Microfluidics/Microactuators, Saarland University, Germany <sup>3</sup>Department for Microsystems Technology, Institute of Sensor and Actuator Systems, Vienna University of Technology, Austria

A17

**Determination of mechanical and swelling properties of epoclad negative photoresist.**

K. Wouters<sup>1</sup>, P. Gijsenbergh<sup>1</sup>, K. Vanstreels<sup>2</sup> and R. Puers<sup>1</sup>

<sup>1</sup>KULEuven, ESAT-MICAS, Belgium <sup>2</sup>IMEC, Belgium

A18

**Graphene for nano-electro-mechanical systems**

Z. Moktadir, S. Boden, H. Mizuta and H. Rutt

University of Southampton, School of Electronics and Computer Science, UK

A19

**Inductive-coupling system for abdominal aortic aneurysms monitoring based on pressure sensing**

A.T. Sepúlveda<sup>1</sup>, A. Moreira<sup>2</sup>, F. Fachin<sup>3</sup>, B.L. Wardle<sup>3</sup>, J.M. Silva<sup>4</sup>, A.J. Pontes<sup>1</sup>, J.C. Viana<sup>1</sup> and L.A. Rocha<sup>1</sup>

<sup>1</sup>I3N/IPC-Institute for Nanostructures, Nanomodelling and Nanofabrication, University of Minho, Portugal <sup>2</sup>University of Porto Faculty of Engineering, Portugal <sup>3</sup>Department of Aeronautics and Astronautics, Massachusetts Institute of Technology, USA <sup>4</sup>INESC Porto, University of Porto Faculty of Engineering, Portugal

Session B  
(Monday 15:00 – 18:00)

B01

**Design and modeling of a three-mass, decoupled, tunable SOI-MEMS gyroscope with sense frame architecture**

I. Sabageh<sup>1</sup>, V. Rajaraman<sup>1</sup>, E. Cretu<sup>2</sup> and P. J. French<sup>1</sup>

<sup>1</sup>Delft University of Technology, Department of Microelectronics, EI Lab- DIMES, The Netherlands <sup>2</sup>University of British Columbia, Department of Electrical and Computer Engineering, Canada

B02

**Robust MEMS for space applications**

A. Delahunty and W.T. Pike

Imperial College London, UK

B03

**Linear variable optical filter with silver metallic layers**

A. Emadi, V.R.S.S. Mokkapati, H. Wu, G. de Graaf and R.F. Wolffenbuttel

Faculty EEMCS, Department ME/EI, Delft University of Technology, The Netherlands

B04

**Fractal-based dual-band small antenna for 2.45 and 5.8 GHz**

S. Ahmed<sup>1</sup>, P. Enoksson<sup>1</sup>, M.V. Rusu<sup>2</sup> and C. Rusu<sup>3</sup>

<sup>1</sup>Chalmers University of Technology, Micro and Nanosystems group, Sweden  
<sup>2</sup>Faculty of Physics, Bucharest University, Romania <sup>3</sup>Imego AB, Sweden

B05

**Measuring thermal properties of small volumes of liquid using a robust and flexible sensor**

J.J. Atherton, M.C. Rosamond, S. Johnstone and D.A. Zeze

Durham University, School of Engineering and Computing Sciences, United Kingdom

B06

**Small antenna based on a MEMS magnetic field sensor that uses a piezoelectric polymer as translation mechanism**

R. Lameiro<sup>1</sup>, F.J.O. Rodrigues<sup>1</sup>, L. Goncalves<sup>1</sup>, S. Lanceros-Mendez<sup>2</sup>, J.H. Correia<sup>1</sup> and P.M. Mendes<sup>1</sup>

<sup>1</sup>Algoritmi, UM, Campus de Azurem, Portugal <sup>1</sup>Center/Department of Physics, University of Minho, Portugal

B07

**Fabrication of integrated bimorphs with self aligned tips for optical switching in 2-D photonic crystal waveguides**

S.M. Chakkalakkal Abdulla<sup>1</sup>, L.J. Kauppine<sup>2</sup>, M. Dijkstra<sup>2</sup>, M.J. de Boer<sup>1</sup>, E. Berenschot<sup>1</sup>, R.M. de Ridder<sup>2</sup> and G.J.M. Krijnen<sup>1</sup>

<sup>1</sup>Transducers Science and Technology, MESA+ Research Institute, University of Twente, The Netherlands <sup>2</sup>Integrated Optical Microsystems Groups, MESA+ Research Institute, University of Twente, The Netherlands

B08

**High-throughput on-chip DNA fragmentation**

L. Shui, M. Jin, J.G. Bomer, E.T. Carlen and A. van den Berg

BIOS/Lab-on-Chip Group, MESA+ Institute for Nanotechnology, University of Twente, The Netherlands

B09

**Performance metrics for MEMS tunable capacitors**

M. Hill<sup>1</sup>, Y. Kubarappa<sup>1</sup> and C. O'Mahony<sup>2</sup>

<sup>1</sup>Adaptive Wireless Systems Group, Cork Institute of Technology, Ireland <sup>2</sup>Tyndall National Institute, University College Cork, Ireland

B10

**Ultrasoft finemet thin films for magneto-impedance microsensors**

J. Moulin<sup>1</sup>, I. Shahosseini<sup>1</sup>, F. Alves<sup>2</sup> and F. Mazaleyrat<sup>3</sup>

<sup>1</sup>IEF, UMR 8622, Univ Paris Sud, France <sup>2</sup>LGEP, UMR 8507, Supelec, France <sup>3</sup>SATIE, UMR 8029, ENS Cachan, France

B11

**3-dimensional etching of silicon substrates using a modified deep reactive ion etching technique**

S. Azimi, J. Naghsh-Nilchi, A. Amini, A. Vali, M. Mehran and S. Mohajerzadeh

School of Electrical and Computer Eng, Thin Film and NanoElectronic Lab, University of Tehran, Iran

B12

**Microshutters for space physics time of flight applications**

K. Brinkfeldt<sup>1</sup>, P. Enoksson<sup>2</sup>, B. Front<sup>2</sup>, M. Wieser<sup>3</sup>, M. Emanuelsson<sup>3</sup> and S. Barabash<sup>3</sup>

<sup>1</sup>Swerea IVF, Sweden <sup>2</sup>Chalmers University of Technology, Dept. Microtechnology and Nanoscience, Sweden <sup>3</sup>Swedish Institute of Space Physics, Sweden

B13

**Study of injection molded surface features in terms of light reflection, wettability and durability**

S. Kuhn, A. Burr, M. Kübler, M. Deckert and C. Bleesen

Heilbronn University, Mechatronics and Micro System Engineering, PIK, Germany

B14

**Simulation studies of parametric amplification in bio-inspired flow sensors**

H. Droogendijk and G.J.M. Krijnen

University of Twente, MESA+ Research Institute, The Netherlands

B15

**Adsorption studies of DNA origami on silicon dioxide**

B. Albrecht<sup>1,2</sup>, D.S. Hautzinger<sup>1,3,4</sup>, M. Krüger<sup>2</sup>, M. Elwenspoek<sup>4,5</sup>, K.M. Müller<sup>3,5</sup> and J.G. Korvink<sup>1,4</sup>

<sup>1</sup>Laboratory for Simulation, Dep. of Microsystems Engineering (IMTEK), <sup>2</sup>Laboratory for Sensors, Dep. of Microsystems Engineering (IMTEK), <sup>3</sup>Laboratory for Synthetic Biosystems, Institute of Biology III, <sup>4</sup>FRIAS, <sup>5</sup>Centre for Biological Signaling Studies (bioss), <sup>1-5</sup>University of Freiburg, Germany

B16

**3D lithography based fabrication of neural stimulator electrode arrays**

F. Ceyssens<sup>1</sup>, J. Verstraete<sup>1</sup>, B. Volckaerts<sup>2</sup> and R. Puers<sup>1</sup>

<sup>1</sup>KULeuven dept. ESAT-MICAS, Belgium. <sup>2</sup>Cochlear Technology Center, Belgium.

B17

**A micro fuel cell stack without interconnect overhead - macro world-like stacks in MEMS**

G. Scotti<sup>1,3</sup>, P. Kanninen<sup>2</sup>, T. Kallio<sup>2</sup> and S. Franssila<sup>3</sup>

<sup>1</sup>Department of Micro and Nanosciences, Aalto University School of Science and Technology, Finland <sup>2</sup>Department of Chemistry, Aalto University School of Science and Technology, Finland <sup>3</sup>Department of Materials Science and Engineering, Aalto University School of Science and Technology, Finland

B18

**Fabrication technique of a compressible biocompatible interconnect using a thin film transfer process**

A.A.A. Aarts<sup>1,2,3</sup>, O. Srivannavit<sup>3</sup>, K.D. Wise<sup>3</sup>, E. Yoon<sup>3</sup>, H.P. Neves<sup>1</sup>, R. Puers<sup>1,2</sup> and C. van Hoof<sup>1,2</sup>

<sup>1</sup>Technology Unit, IMEC, Belgium <sup>2</sup>ESAT-Micas, KU Leuven, Belgium <sup>3</sup>EECS, University of Michigan, USA

B19

**Interference filter based absorber for thermopile detector array by surface micromachining**

H. Wu, A. Emadi, G. de Graaf and R. Wolffenbuttel

Delft University of Technology, Faculty of EEMCS, Department of ME/EI, The Netherlands

B20

**Thermal analysis, fabrication and signal processing of surface micromachined thermal conductivity based gas sensors**

G. de Graaf, H. Wu and R.F. Wolffenbuttel

Delft University of Technology, Faculty EEMCS, Dept. for Micro-Electronics, The Netherlands



Session C  
(Tuesday 9:45 – 12:15)

C01

**High aspect ratio hydrogenation-assisted lateral etching of (100) silicon**

M. Kayyalha, J. Naghsh Nilchi, A. Ebrahimi and S. Mohajerzadeh  
University of Tehran, Nano-Electronics and Thin Film Lab., Iran

C02

**AFM-based mechanical characterization of fbar cantilevers as first step towards developing of force sensors**

C.J. Camargo, H. Campanella, J. Montserrat and J. Esteve  
Instituto de Microelectrónica de Barcelona IMB-CNM (CSIC), Spain

C03

**Post-processing of linear variable optical filter on CMOS chip at die-level**

A. Emadi, H. Wu, G. de Graaf and R. F. Wolffenbuttel  
Faculty EEMCS, Department ME/EI, Delft University of Technology, The Netherlands

C04

**MEMS based gravimeters and gravity gradiometers**

R. Cuperus<sup>1</sup>, F.F. Flokstra<sup>1</sup>, R.J. Wiegerink<sup>2</sup> and J. Flokstra<sup>1</sup>

<sup>1</sup>University of Twente, Interfaces and Correlated Electron systems, The Netherlands

<sup>2</sup>University of Twente, Transducers Science and Technology, The Netherlands

C05

**A musical instrument in MEMS**

J.B.C. Engelen, H. de Boer, J.G. Beekman, A.J. BeenG.A. Folkertsma, L. Fortgens, D. de Graaf, S. Vocke, L.A. Woldering and L. Abelmann

Transducer Science and Technology, MESA+ Institute for Nanotechnology, University of Twente, Enschede, The Netherlands

C06

**Microfluidic chip development for an autonomous field deployable water quality analyser**

D. Maher<sup>1</sup>, J. Healy<sup>1</sup>, J. Cleary<sup>1</sup>, G. Carroll<sup>2</sup> and D. Diamond<sup>1</sup>

<sup>1</sup>CLARITY: Centre for Web Sensing Technologies, Dublin City University, Ireland

<sup>2</sup>EpiSensor Ltd., Ireland

C07

**A novel multisite silicon probe for laminar neural recordings with improved electrode impedance**

A. Pongrácz<sup>1</sup>, G. Márton<sup>1</sup>, L. Grand<sup>2,3</sup>, É. Vázsonyi<sup>1</sup>, I. Ulbert<sup>2,3</sup>, G. Karmos<sup>2,3</sup>, S. Wiebe<sup>4</sup> and G. Battistig<sup>1</sup>

<sup>1</sup>Research Institute for Technical Physics and Materials Science, Hungarian Academy of Sciences, Hungary <sup>2</sup>Peter Pazmany Catholic University, Faculty of Information Technology, Hungary <sup>3</sup>Institute for Psychology of the Hungarian Academy of Sciences, Hungary <sup>4</sup>Plexon Inc., USA

C08

**Large deflection actuator for variable-ratio RF MEMS power divider application**

Y. Li<sup>1</sup>, S. Kühne<sup>1</sup>, D. Psychogiou<sup>2</sup>, J. Hesselbarth<sup>2</sup> and C. Hierold<sup>1</sup>

<sup>1</sup>Micro- and Nanosystems, Department of Mechanical and Process Engineering, ETH Zurich, Switzerland <sup>2</sup>Laboratory for Electromagnetic Fields and Microwave Electronics, Department of Information Technology and Electrical Engineering, ETH Zurich, Switzerland

C09

**PVDF micro heat exchanger manufactured by ultrasonic hot embossing and welding**

K. Burlage, C. Gerhardy and W.K. Schomburg

RWTH Aachen University, Konstruktion und Entwicklung von Mikrosystemen (KEmikro), Germany

C10

**A comb based in-plane SiGe capacitive accelerometer for above-IC integration**

L. Wen<sup>1</sup>, K. Wouters<sup>1</sup>, L. Haspeslagh<sup>2</sup>, A. Witvrouw<sup>2</sup> and R. Puers<sup>1</sup>

<sup>1</sup>ESAT-MICAS, Katholieke Universiteit Leuven, Belgium <sup>2</sup>IMEC, Belgium

C11

**Surface-micromachined gas sensor using thermopiles for carbon dioxide detection**

S. Chen, H. Wu, G. de Graaf and R. F. Wolffenbuttel

Delft University of Technology, Faculty of EEMCS, Department of ME/EI, The Netherlands

C12

**Subwavelength nanopylamids for surface enhanced Raman scattering**

M. Jin<sup>1</sup>, V. Pully<sup>2</sup>, C. Otto<sup>2</sup>, A. van den Berg<sup>1</sup> and E.T. Carlen<sup>1</sup>

<sup>1</sup>BIOS/Lab-on-a-Chip Group, <sup>2</sup>Medical Cell Biophysics Group <sup>1,2</sup>MESA+ Institute for Nanotechnology, <sup>2</sup>MIRA Institute for Biomedical Technology and Technical Medicine, University of Twente, The Netherlands

C13

**A microneedle-based miniature syringe for transdermal drug delivery**

C. O'Mahony, J. Scully, A. Blake and J. O'Brien

Tyndall National Institute, University College Cork, Ireland

C14

**On the processing aspects of high performance hybrid backside illuminated CMOS imagers**

J. De Vos, K. De Munck, K. Minoglou, P. Ramachandra Rao, M.A. Erismis, P. De Moor and D.S. Tezcan

IMEC, Belgium

C15

**Fabrication and characterization of carbon nanotube composites for strain sensor applications**

F. Ceyssens<sup>1</sup>, M. De Volder<sup>2</sup>, G. Keulemans<sup>1</sup>, J.W. Seo<sup>3</sup> and R. Puers<sup>1</sup>

<sup>1</sup>KULeuven, dept. ESAT-MICAS, Belgium. <sup>2</sup>KULeuven, dept. Mech. 2Eng, Belgium <sup>3</sup>KULeuven, dept. MTM, Belgium

C16

**Fluidic variable inductor using SU8 channel**

I. El Gmati<sup>1,3</sup>, P. Calmon<sup>1,2</sup>, R. Fulcran<sup>1</sup>, S. Pinon<sup>1</sup>, A. Boukabache<sup>1,2</sup>, P. Pons<sup>1,2</sup> and A. Kallala<sup>3</sup>

<sup>1</sup>LAAS-CNRS, France <sup>2</sup>Université de Toulouse, UPS, INSA, INP, ISAE, LAAS, France <sup>3</sup>Laboratoire instrumentations Monastir, Tunisie

C17

**Low-cost bevel-shaped sharp tipped hollow polymer-based microneedles for transdermal drug delivery**

B.P. Chaudhri<sup>1,2</sup>, F. Ceyssens<sup>1</sup>, P. De Moor<sup>2</sup>, C. Van Hoof<sup>1,2</sup> and R. Puers<sup>1,2</sup>

<sup>1</sup>ESAT, Department of Electrical Engineering, Katholieke Universiteit Leuven, Belgium <sup>2</sup>IMEC, Belgium

C18

**Non-invasive dry electrodes for EEG**

M.F. Silva, N.S. Dias, A.F. Silva, J.F. Ribeiro, L.M. Goncalves, J.P. Carmo, P.M. Mendes and J.H. Correia

University of Minho, Dept. Industrial Electronics, Portugal

Session D  
(Tuesday 14:45 – 17:15)

D01

**Application of silicon micro-needles in liquid-based sensors and vapor transport**

Z. Sanaee and S. Mohajerzadeh

University of Tehran, School of Electrical and Computer Eng, Nano-electronic Center of Excellence, Thin Film and Nano-Electronic Lab, Iran

D02

**Metallic layer for em pressure sensor sensitivity improvement**

S. Bouaziz<sup>1,2</sup>, M. Mehdi Jatlaoui<sup>1</sup>, D. Mingli<sup>1</sup>, P. Pons<sup>1</sup> and H. Aubert<sup>1,2</sup>

<sup>1</sup>CNRS, LAAS, Toulouse, France <sup>1</sup>Université de Toulouse, INP, LAAS, France

D03

**Microfabrication and characterization of thin-films solid-state rechargeable lithium battery**

J.F. Ribeiro<sup>1</sup>, M.F. Silva<sup>1</sup>, L.M. Goncalves<sup>1</sup>, M.M. Silva<sup>2</sup> and J.H. Correia<sup>1</sup>

<sup>1</sup>University of Minho, Algoritmi Centre, Portugal <sup>2</sup>University of Minho, Chemistry Centre, Portugal

D04

**Determination of young's modulus of PZT- influence of cantilever orientation**

H. Nazeer<sup>1</sup>, L.A. Woldering<sup>1</sup>, L. Abelmann<sup>1</sup> and M.C. Elwenspoek<sup>1,2</sup>

<sup>1</sup>MESA+ institute for nanotechnology, University of Twente, The Netherlands

<sup>2</sup>Freiburg institute for Advanced Studies, Albert-Ludwigs-Universitat Freiburg, Germany

D05

**Tungsten-siliconnitride medium for mega- to gigayear data storage**

J. de Vries<sup>1</sup>, L. Abelmann<sup>1</sup>, A. Manz<sup>2</sup> and M. Elwenspoek<sup>1,2</sup>

<sup>1</sup>MESA+ institute for nanotechnology, University of Twente, The Netherlands

<sup>2</sup>Freiburg institute for Advanced Studies, Albert-Ludwigs-Universitat Freiburg, Germany

D06

**Controlled increase and stabilisation of the tuning range of RF-MEMS capacitors with an active lid electrode**

J. Love<sup>1</sup>, M. Hill<sup>1</sup> and C. O'Mahony<sup>2</sup>

<sup>1</sup>Adaptive Wireless Systems Group, Cork Institute of Technology, Ireland <sup>2</sup>Tyndall National Institute, University College Cork, Ireland

D07

**Two-degree-of-freedom capacitive MEMS velocity sensor: initial test measurements**

A. Alshehri<sup>1</sup>, M. Kraft<sup>1</sup> and P. Gardonio<sup>2</sup>

<sup>1</sup>EDS, University of Southampton, UK <sup>2</sup>DIEGM, Università degli Studi di Udine, Italy

D08

**Computational analysis of microparticle separation in straight channels**

H. Kizil<sup>1</sup>, L. Trabzon<sup>2</sup>, L. Yobas<sup>3</sup>, M. Yilmaz<sup>1</sup> and A. Ozbey<sup>2</sup>

<sup>1</sup>Department of Materials and Metallurgical Engineering, Istanbul Technical University, Turkey <sup>2</sup>Department of Mechanical Engineering, Istanbul Technical University, Turkey <sup>3</sup>Department of Electronic and Computer Engineering, Hong Kong University of Science and Technology, Hong Kong

D09

**Fabrication of cantilever arrays with tips for parallel optical readout**

W.W. Koelmans<sup>1</sup>, T. Peters<sup>1</sup>, L. Abelman<sup>1</sup> and M.C. Elwenspoek<sup>1,2</sup>

<sup>1</sup>MESA+ and IMPACT Research Institutes, University of Twente, The Netherlands  
<sup>2</sup>Freiburg institute for Advanced Studies, Albert-Ludwigs-Universitat Freiburg, Germany

D10

**Morphological characterisation of micromachined film bulk acoustic resonator structures manufactured on GaN/Si**

A. Cismaru<sup>1</sup>, A. Stavrinidis<sup>2</sup>, A. Stefanescu<sup>1</sup>, D. Neculoiu<sup>1</sup>, G. Konstantinidis<sup>2</sup> and A. Müller<sup>1</sup>

<sup>1</sup>IMT-Bucharest, Romania <sup>2</sup>FORTH-IESL-MRG Heraklion, Greece

D11

**Static crack growth and fatigue modeling for silicon MEMS**

W.M. van Spengen

TU Delft, 3mE-PME, The Netherlands

D12

**Development of a novel micromirror with high static rotation angle for measurement applications**

S. Weinberger, O. Jakovlev, C.H. Winkelmann, E. Markweg and M. Hoffmann

Ilmenau University of Technology, IMN MacroNano, Department of Micromechanical Systems, Germany

D13

**Applications of all-(111) surface silicon nanowires**

M. N. Masood, S. Chen, E. T. Carlen and A. van den Berg

BIOS Lab on a Chip, MESA+ Institute for Nanotechnology, University of Twente, The Netherlands

D14

**A micromirror for optical projection displays**

R.A. Brookhuis<sup>1</sup>, M.J. de Boer<sup>1</sup>, M. Dijkstra<sup>1</sup>, A.A. Kuijpers<sup>2</sup>, D. van Lierop<sup>2</sup> and R.J. Wiegerink<sup>1</sup>

<sup>1</sup>MESA+ institute for nanotechnology, University of Twente, The Netherlands

<sup>2</sup>Philips Applied Technologies, Eindhoven, The Netherlands

